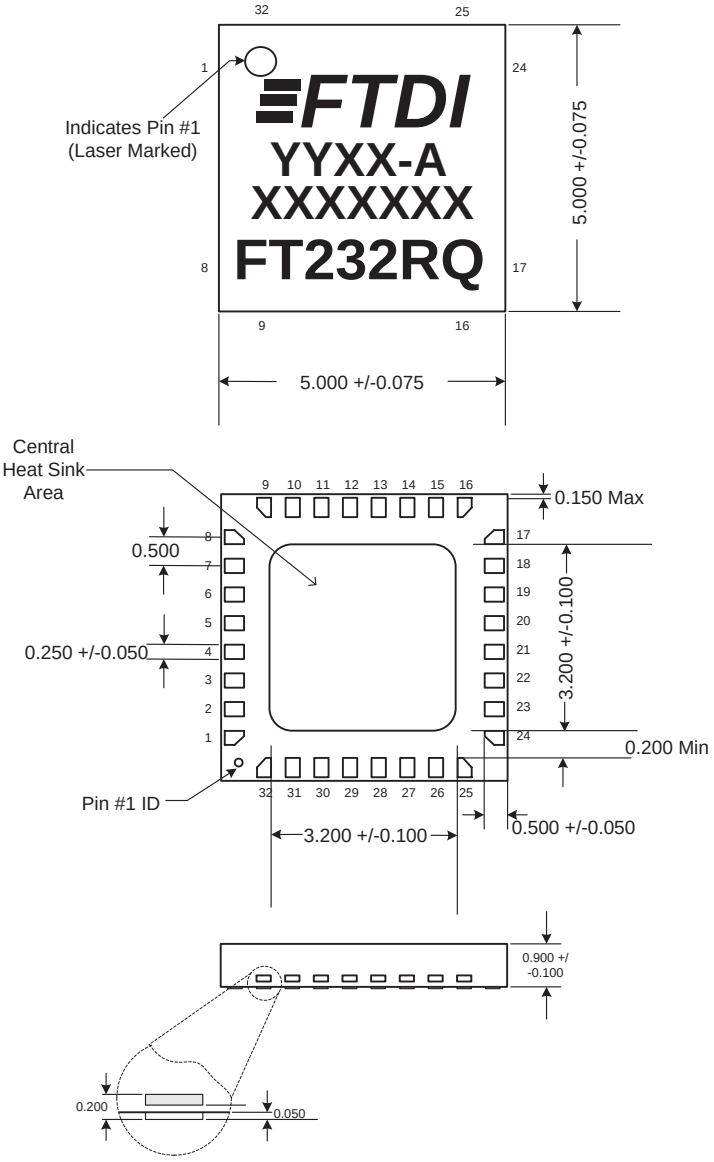
9.2 QFN-32 Package Dimensions



Note: The pin #1 ID is connected internally to the device's central heat sink area . It is recommended to ground the central heat sink area of the device.

Dimensions in mm.

Figure 9.2 QFN-32 Package Dimensions

The FT232RQ is supplied in a RoHS compliant leadless QFN-32 package. The package is lead (Pb) free, and uses a 'green' compound. The package is fully compliant with European Union directive 2002/95/EC.

This package is nominally 5.00mm x 5.00mm. The solder pads are on a 0.50mm pitch. The above mechanical drawing shows the QFN-32 package. All dimensions are in millimetres.

The centre pad on the base of the FT232RQ is not internally connected, and can be left unconnected, or connected to ground (recommended).

The date code format is **YYXX** where XX = 2 digit week number, YY = 2 digit year number.

The code **XXXXXXX** is the manufacturing LOT code. This only applies to devices manufactured after April 2009.

9.3 QFN-32 Package Typical Pad Layout

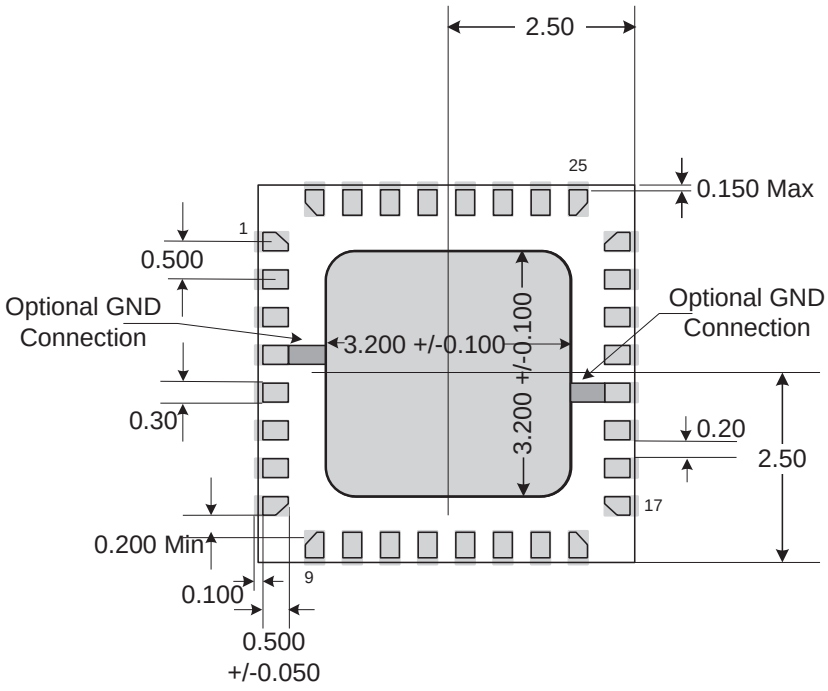


Figure 9.3 Typical Pad Layout for QFN-32 Package

9.4 QFN-32 Package Typical Solder Paste Diagram

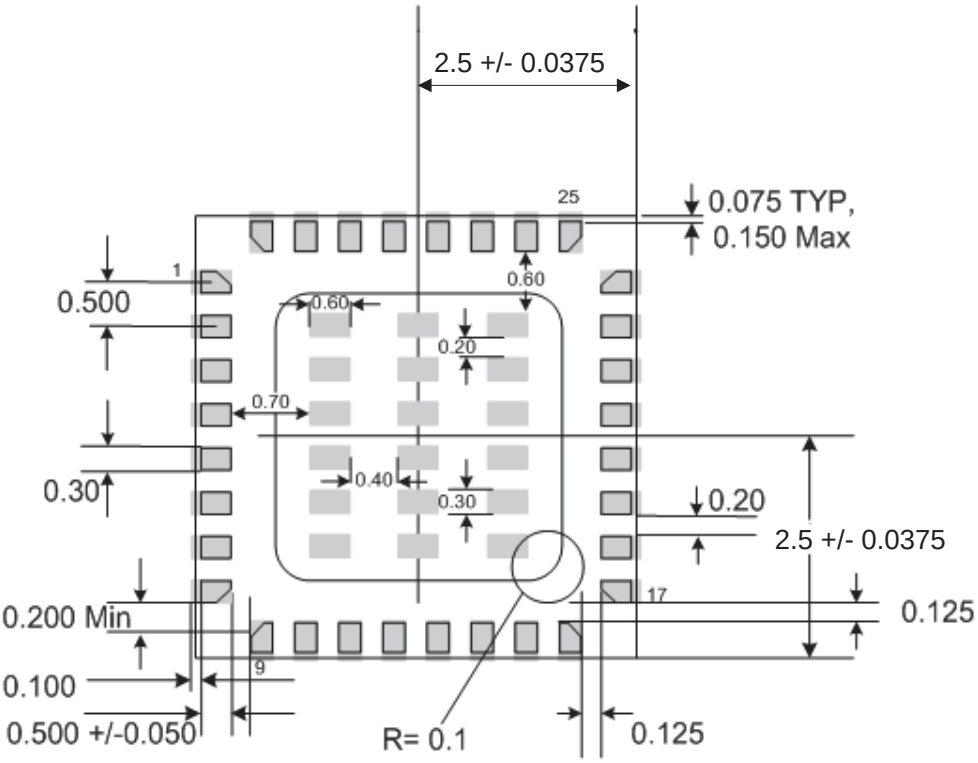


Figure 9.4 Typical Solder Paste Diagram for QFN-32 Package